

Product Change Notification Number: PDF-032

Notification Date: August 01, 2017

Title: Manufacturing Capacity Expansion for the 8-contact, 6 x 8mm, Very Thin Dual Flat No Lead Package (VDFN)					
Product Identification:					
Specific Adesto products offered in the 6x8 mm VDFN package (part number package suffix 'MW').					
See Table I for a complete list of affected Adesto part numbers.					
Reason For Change	☑ Capacity Expansion	☑ Design	☑ Manufacturing Location		
	□ Material / Composition	Processing/Manufacturing	□ Quality & Reliability		
Change Description: Addition of a qualified subcontractor for assembly and final electrical test services for products offered in the VDFN 6x8 mm package selection to further expand capacity.					
NO external package dimensional changes, that would affect PCB board layout or device functionality, occur with this change (see Figure 1 for package thermal pad dimensions).					
Quantifiable Impact on Quality & Reliability:					
No change in Quality or Rel	No change in Quality or Reliability				
Affected products remain Form	m, Fit and Functionally compatible	with the same products assembl	ed in existing facilities.		
There is no impact on product	availability or pricing				
Facility and Location:		Greatek Zhunan, Taiwan			
Certification:		ISO 9001, ISO/TS16949 & ISO 14001			
Affected Products:		See Table I of this Notice			
Last Time Buy: 🗹 Not Applicable 🗆 Applicable					
Implementation Date: See Table I					
Identification: Date Code Assembly ID Part Marking (backside) Ordering Part Number					
Qualification Report: : Available Now See Table I for availability Not Applicable					
Request the qualification report at pcn@adestotech.com					
Product Samples: Available Now See Table I for availability Not Applicable					
To order samples, message <u>pcn@adestotech.com</u> or contact an authorized distributor or Adesto manufacturing Representative.					
CUSTOMER ACKNOWLEDGEMENT OF RECEIPT: Adesto requests your acknowledgement of the receipt of this Notice. Please email to <u>PCN@adestotech.com</u> to grant approval or request additional information. Adesto will deem this change accepted unless specific conditions of acceptance are received via an email addressed to <u>PCN@adestotech.com</u> within 30 days from the date of this notice.					

FIGURE 1 PACKAGE DIMENSIONAL CHANGES (published datasheet updated)

NO critical external package dimensional changes.

The minimum dimensions of the thermal pad have reduced as shown below. Impact to board layout: NONE

These changes have no impact on board layout due to industry standard recommendation not to run PCB traces under the pad area.



Table 1: Affected Part Numbers

	Samples		
Datasheet Part Number	Available	Qualification Report Available	Production Implementation Date
AT45DB321E-MWHF-Y	Sep 30, 2017	October 1, 2017	December 1, 2017
AT45DB321E-MWHF-T	Sep 30, 2017	October 1, 2017	December 1, 2017
AT45DB321E-MWHF2B-T	Sep 30, 2017	October 1, 2017	December 1, 2017
AT45DQ321-MWHF-Y	Sep 30, 2017	October 1, 2017	December 1, 2017
AT45DQ321-MWHF-T	Sep 30, 2017	October 1, 2017	December 1, 2017
AT45DQ321-MWHF2B-T	Sep 30, 2017	October 1, 2017	December 1, 2017
AT45DQ321-MWHFHJ-T	Sep 30, 2017	October 1, 2017	December 1, 2017
AT45DQ321-MWHFHK-T	Sep 30, 2017	October 1, 2017	December 1, 2017
AT45DB641E-MWHN-Y	Sep 30, 2017	October 1, 2017	December 1, 2017
AT45DB641E-MWHN-T	Sep 30, 2017	October 1, 2017	December 1, 2017
AT45DB641E-MWHN2B-T	Sep 30, 2017	October 1, 2017	December 1, 2017